

**AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph beginning at page 3, line 18, with the following rewritten paragraph.

The present invention is a processing apparatus for processing a substrate on a surface of which a film is formed, comprising: a film removing member for selectively removing the film on a predetermined portion of an outer peripheral part of the substrate; and a rotating mechanism for rotating the substrate, the film removing member having a shape which is composed of a vertical part, an upper part formed in a horizontal direction from an upper end part of the vertical part, and a lower part formed in a same direction as the horizontal direction from a lower end part of the vertical part, being formed so that the outer peripheral part of the substrate is allowed to be inserted into an opening which is formed by the upper part and the lower part, and including a plasma supply part for supplying plasma of a reactive gas to the film on the predetermined portion and a suction port for sucking an atmosphere in a vicinity of the predetermined portion from outside the substrate, and the plasma supply part being attached to a ceiling surface inside the film removing member surrounded by the vertical part, the upper part, and the lower part. Incidentally, the plasma supply part may be what jets gas which is previously converted into plasma to the film on the outer peripheral part of the substrate or may be what converts a reactive gas in the vicinity of the outer peripheral part of the substrate into plasma and supplies the plasma indirectly to the outer peripheral part of the substrate. --

Please replace the paragraph beginning at page 3, line 18, with the following rewritten paragraph.

According to the present invention, by inserting the outer peripheral part of the substrate into the film removing member, rotating the substrate side by the rotating mechanism, and supplying the plasma from the ceiling surface inside the film removing member, it is possible to supply the reactive plasma to the film on the predetermined portion of the outer peripheral part of the substrate and chemically react the plasma with the film on the

predetermined portion. Further, it is possible to separate the film by the chemical reaction and remove components of the separated film from the suction port. Furthermore, it is possible to form an atmospheric current which goes to the outside above the outer peripheral part of the substrate by suction from the supply port and guide the plasma supplied from the plasma supply part. Accordingly, by combining the supply and the guidance of the plasma, for example, it becomes possible to bring the atmospheric current which carries the plasma into oblique contact with an end part of the film on the outer peripheral part of the substrate and form a sloped part at the end part of the film. As a result, for example, even if a polishing pad is pressed on the substrate in the aforementioned polishing processing, a load does not concentrate on the vicinity of the end part of the film, which can prevent, for example, a hard mask as an upper film from peeling off. Moreover, the film remaining on the surface of the outer peripheral part of the substrate after the aforementioned outer peripheral film removing processing can be removed. As a result, the later adhesion between the surface of the outer peripheral part and the hard mask or the like as the upper film improves. Hence, even if the polishing pad is pressed on the surface of the outer peripheral part, the peeling of the hard mask or the like can be prevented. --

Please replace the paragraph beginning at page 5, line 3, with the following rewritten paragraph.

~~It is also possible that the film removing member has a shape which is composed of a vertical part, an upper part formed in a horizontal direction from an upper end part of the vertical part, and a lower part formed in the same direction as the horizontal direction from a lower end part of the vertical part, and is formed so that the outer peripheral part of the substrate is allowed to be inserted into an opening which is formed by the upper part and the lower part, and that the plasma supply part is attached to a ceiling surface inside the film removing member surrounded by the vertical part, the upper part, and the lower part. In this case, by inserting the outer peripheral part of the substrate inside the film removing member and supplying the plasma from the ceiling surface, the aforementioned formation of the slope part at the end part of the film and removal of the residue can be performed. Incidentally, the suction port may be provided inside the film removing member and at a position facing the opening.~~

Please replace the paragraph beginning at page 6, line 4, with the following rewritten paragraph.

~~The processing apparatus may further comprise a rotating mechanism for rotating the substrate, and in this case, it is possible to place the film removing member at a specific position of the outer peripheral part of the substrate and remove the film on the outer peripheral part of the substrate by rotating the substrate side. Moreover, the processing apparatus may further~~ comprise a horizontal driving part for horizontally moving the film removing member. This horizontal driving part allows the film removing member to come close to or go away from the substrate. Accordingly, the film removing member can get access to the outer peripheral part of the substrate at a predetermined timing. Moreover, this horizontal driving part makes it possible to arbitrarily determine a removal range of the film on the outer peripheral part of the substrate and remove the film in a predetermined region on the outer peripheral part side of the substrate in accordance with a process. Further, a laser mark part in which substrate identification information such as a lot number, characteristics or the like of the substrate and a cut-out part (notch part) provided in the outer peripheral part of the substrate to facilitate the determination of the crystal orientation of the substrate can be partially removed.

Please delete the paragraph beginning at page 8, line 1.